L Number	Hits	Search Text	DB	Time stamp
1	4	6491518.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 09:49
8	8	"silicon jig"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 09:50
15	215	"glass jig" or "semiconductor jig"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 10:16
22	214	("glass jig" or "semiconductor jig") not "silicon jig"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 09:53
29	90	(("glass jig" or "semiconductor jig") not "silicon jig") and (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 09:53
36	1	"si jig"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 10:15
43	2889	((glass or semiconductor) with jig) not ((("glass jig" or "semiconductor jig") not "silicon jig") and (wafer or substrate)) and (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 10:19
50	301	((glass or semiconductor) near1 jig) not ((("glass jig" or "semiconductor jig") not "silicon jig") and (wafer or substrate)) and (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 10:19
57	5	((glass or semiconductor) near1 (jig and made)) not ((("glass jig" or "semiconductor jig") not "silicon jig") and (wafer or substrate)) and (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 10:20
64	808	((glass or semiconductor) with (jig and made)) not ((("glass jig" or "semiconductor jig") not "silicon jig") and (wafer or substrate)) and (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 10:21
71	513	((glass or semiconductor) with (jig and made and material)) not ((("glass jig" or "semiconductor jig") not "silicon jig") and (wafer or substrate)) and (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 10:22
78	81	((glass or semiconductor) with (jig and made and material and contaminat$3)) not ((("glass jig" or "semiconductor jig") not "silicon jig") and (wafer or substrate)) and (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 10:23